1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP

Package type industry code WLCSP6

Package style descriptive code UC (uncased chip)

Package body material type X (other)

Mounting method type S (surface mount)

Issue date13-4-2017Manufacturer package codeWLCSP6

Table 1. Package summary

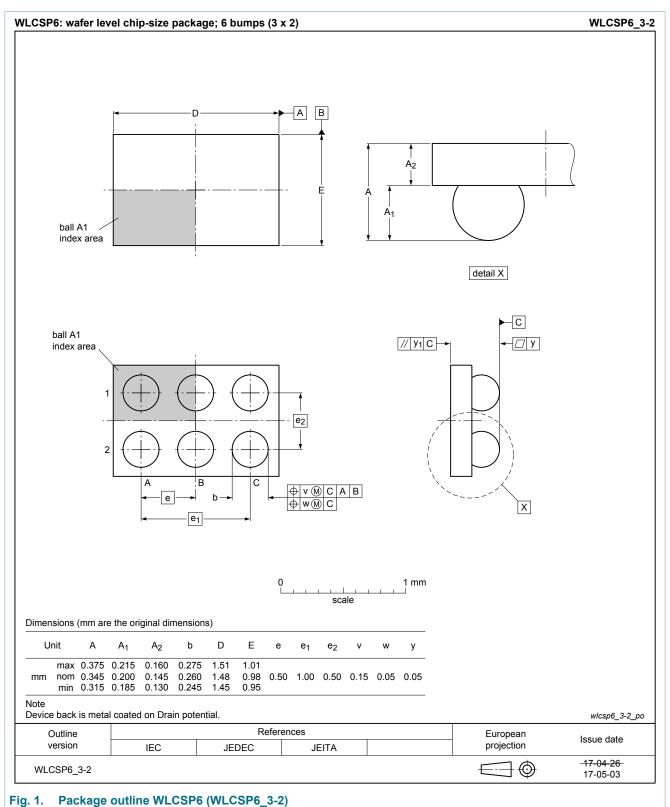
| Symbol | Parameter | Min | Тур | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-------|-------|------|
| D | package length | 1.45 | - | 1.48 | 1.51 | mm |
| E | package width | 0.95 | - | 0.98 | 1.01 | mm |
| Α | seated height | 0.315 | - | 0.345 | 0.375 | mm |
| A ₂ | package height | 0.13 | - | 0.145 | 0.16 | mm |
| е | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 6 | - | |



Nexperia WLCSP6_3-2

wafer level chip-size package; 6 bumps (3 x 2)

2. Package outline



Nexperia WLCSP6_3-2

wafer level chip-size package; 6 bumps (3 x 2)

3. Soldering

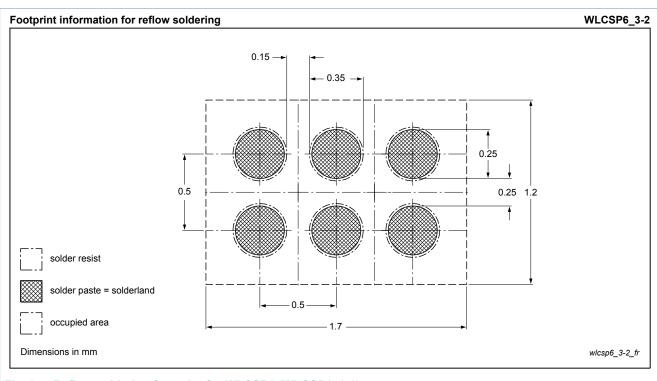


Fig. 2. Reflow soldering footprint for WLCSP6 (WLCSP6_3-2)

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Nexperia WLCSP6 3-2

wafer level chip-size package; 6 bumps (3 x 2)

4. Legal information

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Nexperia WLCSP6_3-2

wafer level chip-size package; 6 bumps (3 x 2)

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